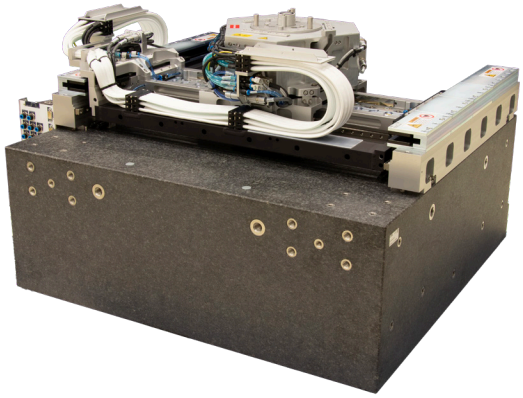
ETEL

More info

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Bidirectional repeatability
±0.4 µm

Position stability
±25 nm

Maximum speed and acceleration
1.2 m/s
20 m/s²

METIS CIP

Planar platform air & mechanical bearing

For step and scan semiconductor and photonic applications

Introducing METIS CIP, a state-of-the-art hybrid planar air & mechanical bearing platform designed for step and scan applications, ensuring unparalleled accuracy, move & settle times and position stability over 4 degrees of freedom.

The METIS CIP platform is a cutting-edge hybrid planar air & mechanical bearing platform, dedicated to step and scan applications with motion in four axes: X, Y, Z, and Theta directions. Its dynamic flatness over the full travel range and bidirectional repeatability make it ideal for high-precision tasks. METIS CIP is widely used in Wafer Process Control applications such as Critical Dimension and Thin Film Metrology, Wafer Scribing, and Wafer Laser Thermal Annealing.
Thanks to 20 years experience of production and technical support, the METIS CIP design combines the accuracy of air bearing technology with the robustness and serviceability of mechanical guiding systems.

HIGH BIDIRECTIONAL REPEATABILITY & ACCURACY
Thanks to the repeatability performance with mapping, METIS CIP can reach an accuracy of ±1 µm on the overall wafer area.

HIGH ACCELERATION FOR HIGHER THROUGHPUT
Upgraded ironless motors deliver accelerations up to 2 g, increasing throughput.

IMPROVED ROBUSTNESS AND SERVICEABILITY
Designed to facilitate maintenance access, and easily replaceable FRUs, METIS CIP benefits from decades of experience, making it a robust production-proven platform.

MINIMIZE CONTAMINATION RISK AT WAFER LEVEL
The new module is designed to prevent any contamination risk at wafer level.

- **METIS CIP planar air bearing guiding system guarantees precise vertical straightness**
- **Module box under vacuum, with special labyrinth design to prevent any contamination risk at wafer level**
- **Unlimited rotation in theta, ensuring shortest time to reach any point on a wafer. New bearing design improving radial runout**
- **Fine Z axis magnet compensation minimize heat transfer to the chuck level**
- **Reinforced motors for high duty cycle at 2 g with a minimized thermal drift**
- **Lift pin axis for loading / unloading wafer, with absolute encoder position to manage safety in any situation**
- **Integration with QUIET Active Isolation System, for the best immunity to floor vibrations and highest process stability**
- **Short move and settle times**